



Final Product Change Notification **Update**

202103024F01U01 : S12VR64/48 FAB SITE EXPANSION (NXP-ATMC to TSMC10)

Note: This notice is NXP Company Proprietary.

Issue Date: Jun 15, 2021 **Effective date:** Jun 16, 2021



Here is your personalized notification about a NXP general announcement.

For detailed information we invite you to [view this notification online](#)

Management summary

This FPCN is updated to inform users that the Reference Manual for the product has been updated to include mask set information of TSMC10 fab site. Please see section "Update Information *" for further details.

Change Category

- | | | | | |
|--|---|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata |
| <input checked="" type="checkbox"/> Wafer Fab Location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | | | | |
| <input checked="" type="checkbox"/> Other: Reference Manual and Errata updated to include TSMC10 mask set information. | | | | |

PCN Overview

Description

NXP Semiconductors is announcing the introduction of Taiwan Semiconductor Manufacturing Company Fab 10 (TSMC10), Shanghai, China as a dual source wafer manufacturing location for the S912VR64/48.

NXP Semiconductors requires the use of Flex part numbers to maximize supply continuity. Without the use of Flex part numbers, backlog will have to be converted from one fab sourced device to another fab sourced device as capacity dictates.

The current Reference Manual rev4.3 will be updated by adding TSMC10 mask set (0P79C) in sections 1.61 Part ID Assignments, 1.11 Module Device level Dependencies and Part Ordering Information. Please see the attached file "RM Update For MC9S12VR to Include TSMC10". An update to this PCN will be issued when the final version of the Reference Manual has been added

into NXP.com.

Errata for S912VR64/48 has been updated and can be found at https://www.nxp.com/products/processors-and-microcontrollers/additional-mpu-mcus-architectures/s12-magniv-mixed-signal-mcus/s12vr-mixed-signal-mcu-for-automotive-industrial-relay-based-motor-control:S12VR?fsp=1&tab=Documentation_Tab

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02, SEM-PW-08, SEM-PW-13

Reason

The Fab manufacturing site capacity expansion to TSMC10 will improve NXP's ability to meet increasing customer demand and still maintain supply from the original Fab (NXP-ATMC).

Identification of Affected Products

Top Side Marking

The mask marking for TSMC10 will reflect P79C, while the mask marking for ATMC will remain N59H.

Product Availability

Sample Information

Samples are available from Apr 20, 2021

Please see the attachment "S12VR64_48_ATMC to TSMC10 Fab Expansion_FPCN_Supplement" file for sample part numbers available for ordering.

Production

Planned first shipment Jul 05, 2021

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Fab Expansion. No Depletion of Inventory required.

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jul 15, 2021.

Update Information

The Reference Manual rev4.3 has been updated to rev4.4 by adding TSMC10 mask set (0P79C) in sections 1.61 Part ID Assignments, 1.11 Module Device level Dependencies and Part Ordering Information.

This document is attached to this FPCN update or can be downloaded from

https://www.nxp.com/products/processors-and-microcontrollers/additional-mpu-mcus-architectures/s12-magniv-mixed-signal-mcus/s12vr-mixed-signal-mcu-for-automotive-industrial-relay-based-motor-control:S12VR?fsp=1&tab=Documentation_Tab

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Dixon Xie
Position	Product Engineer
e-mail address	dixon.xie@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply .

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006- 2021 NXP Semiconductors. All rights reserved.